IMPRESORA BAMBULAB H2C CON SISTEMA VORTEK, AMS 2 PRO Y POTENTE LASER DE 40W PARA IMPRESION PROFESIONAL Y CORTE PROFUNDO EN MATERIALES DE MAYOR DENSIDAD

BAMBULAB-H2CL-40W-COMBO

Descripción

Impresora BambuLab H2C con sistema Vortek, AMS 2 Pro y potente láser de 40W para impresión profesional y corte profundo en materiales de mayor densidad.

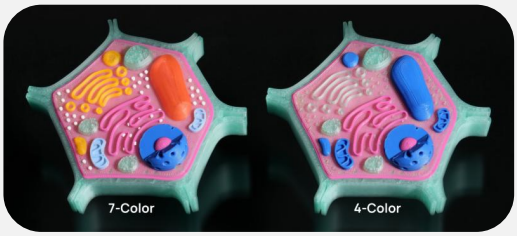
Características del producto

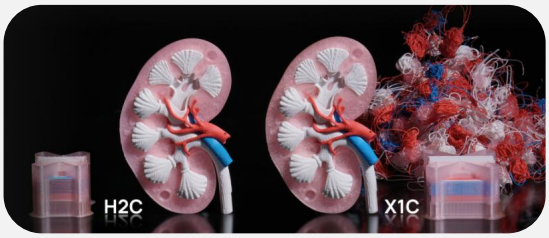
- Cambio de hotend Impresión multimaterial
- Impresión multicolor con mínimo desperdicio de purga
- Calentamiento inductivo de boquillas rápido y preciso
- Extrusora servo de bucle cerrado
- Detección de errores de IA en la ruta completa del filamento
- Boquillas de 350°C y cámara calentada activa de 65°C
- Módulo láser y de corte opcional de 40W
- Volumen de construcción: 330 x 320 x 325 mm³

Item	Specification	
Printing Technology	Fused Deposition Modeling	
Body	Build Volume (W*D*H)	Single Nozzle Printing: 305*320*325 mm³ Dual Nozzle Printing: 300*320*325 mm³ Total Volume for Two Nozzles: 330*320*325 mm³
	Chassis	Aluminum and Steel
	Outer Frame	Plastic and Glass
Physical Dimensions	Physical Dimensions	492*514*626 mm³
	Net Weight	32.5 kg
Toolhead	Extruder Gear	Hardened Steel
	Nozzle	Hardened Steel
	Max Nozzle Temperature	350 °C
	Supported Nozzle Diameter	0.2 mm, 0.4 mm, 0.6 mm, 0.8 mm
	Filament Cutter	Built-in
	Filament Diameter	1.75 mm
	Extruder Motor	Bambu Lab High-precision Permanent Magnet Synchronous Motor
Heatbed	Build Plate Material	Flexible Steel Plate
	Included Build Plate Type	Textured PEI Plate
	Supported Build Plate Type	Textured PEI plate, Engineering Plate
	Max Heatbed Temperature	120 °C
Speed	Max Speed of Toolhead	1000 mm/s
	Max Acceleration of Toolhead	20,000 mm/s²
	Max Flow for Hotend	40 mm³/s (Test parameters: 250 mm round model with a single outer wall; Bambu Lab ABS; 280 °C printing temperature)
Chamber Temperature Control	Active Chamber Heating	Supported
	Max Temperature	65 °C
Air Purification	Pre-filter Grade	G3
	HEPA Filter Grade	H12
	Activated Carbon Filter Type	Granulated Coconut Shell
	VOC Filtration	Superior
	Particulate Matter Filtration	Supported
Cooling	Part Cooling Fan	Closed Loop Control
	Cooling Fan for Hotend	Closed Loop Control
	Main Control Board Fan	Closed Loop Control
	Chamber Exhaust Fan	Closed Loop Control
	Chamber Heat Circulation Fan	Closed Loop Control
	Auxiliary Part Cooling Fan	Closed Loop Control
	Toolhead Enhanced Cooling Fan	Closed Loop Control
Supported Filament Type	PLA, PETG, TPU, PVA, BVOH, ABS, ASA, PC, PA, PET, PPS;Carbon/Glass Fiber Reinforced PLA, PETG, PA, PET, PC, ABS, ASA, PPA, PPS	

Sensor	Live View Camera	Built-in; 1920*1080
	Nozzle Camera	Built-in; 1920*1080
	BirdsEye Camera	Built-in; 3264*2448
	Toolhead Camera	Built-in; 1920*1080
	Door Sensor	Supported
	Filament Run Out Sensor	Supported
	Filament Tangle Sensor	Supported
	Filament Odometry	Supported with AMS
	Power Loss Recovery	Supported
Electrical Requirements	Voltage	100-120 VAC / 200-240 VAC, 50/60 Hz
	Max Power*	1800 W@220 V/1250 W@110 V
	Typical Power	200 W@220 V/200 W@110 V (Single Nozzle Printing PLA)
Working Temperature	10 ℃-30 ℃	
Electronics	Touchscreen	5-inch 720*1280 Touchscreen
	Storage	Built-in 8 GB EMMC and USB Port
	Control Interface	Touchscreen, mobile App, PC App
	Motion Controller	Dual-core Cortex-M4 and Single-core Cortex-M7
	Application Processor	Quad-core 1.5 GHz ARM A7
	Neural Processing Unit	2 TOPS
Software	Slicer	Bambu StudioSupports third-party slicers which export standard G-code, such as Super Slicer, PrusaSlicer and Cura, but certain advanced features may not be supported.
	Supported Operating System	MacOS, Windows, Linux
Network Control	Ethernet	Not Available
	Wireless Network	Wi-Fi
	Network Kill Switch	Not Available
	Removable Network Module	Not Available
	802.1X Network Access Control	Not Available
Wi-Fi	Operating Frequency	2412 - 2472 MHz, 5150 - 5850 MHz (FCC/CE)2400 - 2483.5 MHz, 5150 - 5850 MHz (SRRC)
	Wi-Fi Transmitter Power (EIRP)	2.4 GHz: < 23 dBm (FCC); < 20 dBm (CE/SRRC/MIC)5 GHz Band1/2: < 23 dBm (FCC/CE/SRRC/MIC)5 GHz Band3: < 30 dBm (CE); < 24 dBm (FCC)5 GHz Band4: < 23 dBm (FCC/SRRC); < 14 dBm (CE)
	Wi-Fi Protocol	IEEE 802.11 a/b/g/n

Aplicaciones





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